



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Gene R. Anderson, et al.

Serial No.: 09/749,285

Group Art Unit: 2874

Filed: December 26, 2000

Examiner: Unknown

For: Housing and Mounting Structure

White & Case Docket No.: 1613370-0012

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Christina Ishihara

Name

Signature

August 12, 2003

Date

INFORMATION DISCLOSURE STATEMENT

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Sir:

In accordance with the duty of disclosure imposed by 37 C.F.R. § 1.56 to inform the Patent Office of all references coming to the attention of Applicants or attorneys or agents for Applicants which are or may be material to the examination of the subject application, Attorneys for Applicants hereby invite the Examiner's attention to the reference(s) listed on the accompanying PTO Form SB/08A.

Identification of references listed on the attached PTO form is not to be construed as an admission of Applicants or attorneys for Applicants that such references are material or available as prior art against the subject application. The right is reserved to antedate any item in accordance with standard procedure.

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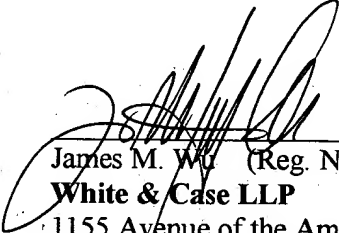
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This submission is understood to complement the results of the Examiner's own independent search. The submission should not be construed as a representation that a search was made, or that the cited items are inclusive of all the relevant and material citations that may be available publicly.

Copies of the cited references are enclosed. Applicants respectfully request that the Examiner review the attached references and that they be made of record in the file history of the above-captioned application.

In connection with the filing of this Information Disclosure Statement, Applicants believe that there is no fee due. However, should there be a required fee the Commissioner is hereby authorized to charge White & Case LLP Deposit Account No. 23-1703.

Dated: August 12, 2003



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Substitute for form 1449A/PTO				Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Application Number	09/749,285
				Filing Date	December 26, 2000
				First Named Inventor	Gene R. Anderson
				Group Art Unit	2874
(use as many sheets as necessary)				Examiner Name	Unknown
Sheet	1	of	3	Attorney Docket Number	1613370-0012
U.S. PATENT DOCUMENTS					
Examiner Initials *	Cite No.	Document Number Number-Kind Code ² (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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Examiner Signature	T L E	Date Considered	5/20/04
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¹ Unique citation designation number. ² See attached Kinds of U.S. Patent Documents. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

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